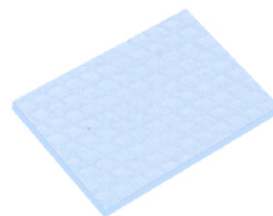


Ther TP300-3-55

Soft, Conductive Gap Filler Pad

TP300-3-55 an extremely soft gap filler pad that also harnesses exceptional thermally conductive characteristics. TP300-3-55 can meet the design needs of numerous design requirements and specifications. TP300-3-55 will provide the innate thermal requirements your design needs without over stressing the components or cases.



Features and Benefits

- 3.0 W/m.K
- Ultra soft and highly compliant
- Naturally tacky, easing application
- High electrical insulation
- Good temperature resistance

Typical Applications

- Networking and Telecommunications
- IT: Notebooks, Tablets, Power Conversion
- Industrial: LEDs, Power Supplies and Conversion
- Automotive: Control Modules, Turbo Actuators
- Consumer Electronics: Gaming Systems, LCDs, and Graphic Cards

HOW TO ORDER

Patron THER TP300-3-55 XXX-YYY-ZZmm

XXX = width in mm

YYY = depth in mm

ZZ = thickness in mm

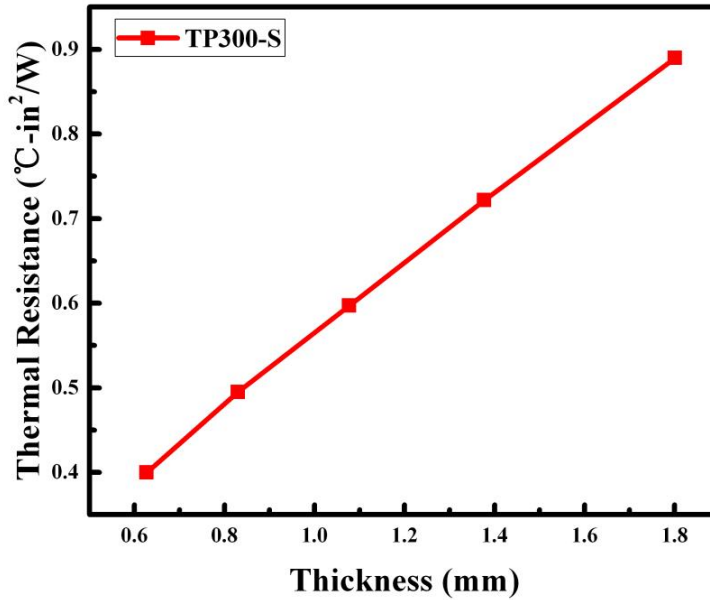
TYPICAL PROPERTIES

Attribute	Value	Test Method
	TP300-3-55	-
Composition	Ceramic Filler + Silicone	-
Color	Light Blue	Visual
Thickness (mm)	0.5 to 10.0	ASTM D374
Density (g/cc)	3.0	ASTM D792
Hardness (Shore OO)	55(Thickness≥1.0 Shore OO 40)	ASTM D2240
Usage Temperature (°C)	- 40 to 150	-
Electrical		
Breakdown Voltage (kV/mm)	>5.0	ASTM D149
Volume Resistivity (Ω.cm)	10 ¹³	ASTM D257
Dielectric Constant @1MHz	7.3	ASTM D150
Flammability	V-0	UL 94
Thermal		
Thermal Conductivity (W/m.K)	3.0	ISO 22007-2

Soft, Conductive Gap Filler Pad

Thickness vs. Thermal Resistance

Reference only



Pressure vs. Deflection

Reference only

